

■ Features

- Molding Inductor.
- High reliability.
- High current, low DCR, high efficiency.
- Very low acoustic noise and very low leakage flux noise.
- Operating temperature:-55℃ ~ +125℃ (Including self-temperature rise) .

■ Applications

- General Electronic.
- Video Device,TV,TFT.
- Power Module for PC.
- NB/Lap Top Computer.
- Server,VGA Card/Module.
- DC/DC converter.

■ Product Identification

YSPIT □□□□□ — □□□ □
 (1) (2) (3) (4)

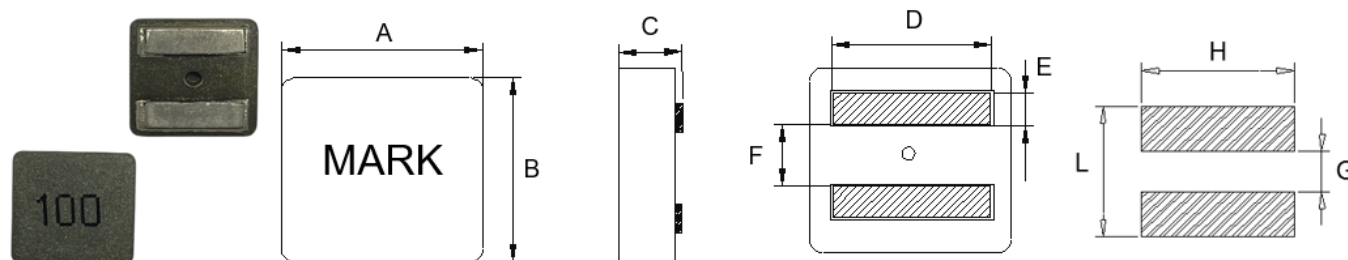
(1) : Type

(2) : Dimensions

(3) : Inductance value

(4) : Inductance Tolerance: N=±30%,M=±20%

■ Shapes and Dimensions (Unit: mm)



TYPE	A	B	C	D	E	F	G Ref.	H Ref.	L Ref.
YSPIT0630A	6.6±0.2	6.4±0.2	2.8±0.3	5.5±0.8	1.4±0.3	2.6±0.3	2.5	5.6	5.6

■ Electrical Characteristics

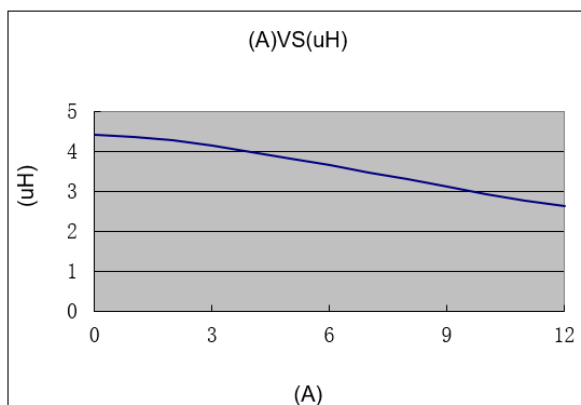
Part Number	Inductance (μH) @100KHz/0.1V	DCR Max. ($\text{m}\Omega$)	I sat (Typ.)	I rms (Typ.)
YSPIT0630A-4R7M	4.7 $\pm$ 20%	26.0	9.0	6.0

- ※ Isat: DC current (A) that will cause L0 to drop approximately 30% TYP.
- ※ Irms: DC current (A) that will cause an temperature rise ΔT approximate to 40°C.
- ※ All test data is referenced to 25°C ambient.
- ※ Absolute maximum voltage 30VDC.

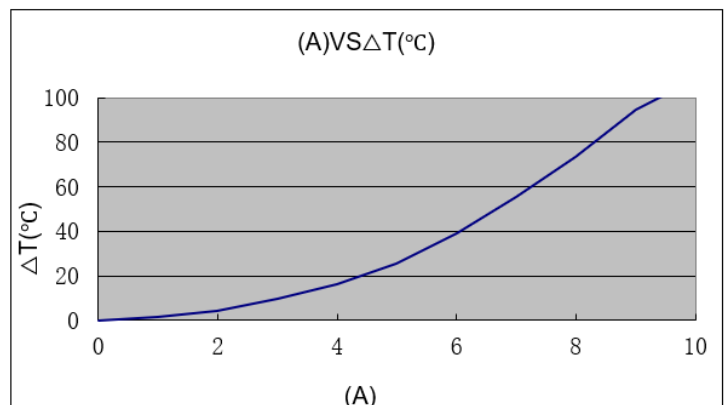
■ Material List

NO.	ITEM	DESCRIPTION	SUPPLIER	REMARK
1	BASE	Copper wire+Solder	AI QUAN Or Equal	
2	WIRE	Polyester Wire	SONGTIAN Or Equal	
3	CORE	Metal composite core	YJYCOIN Or Equal	
4	MARKING	BLACK	HUI QUAN Or Equal	
5	COVER TAPE	13.3mm	XX Or Equal	Transparent, heat sealed
6	CARRIER TAPE	TC0630-W16P12-TC	XX Or Equal	Transparent (with holes)

■ Curve Graph



Current Value vs. Inductance Value Curve



Current Value vs. Temperature Curve

■ Mechanical Reliability

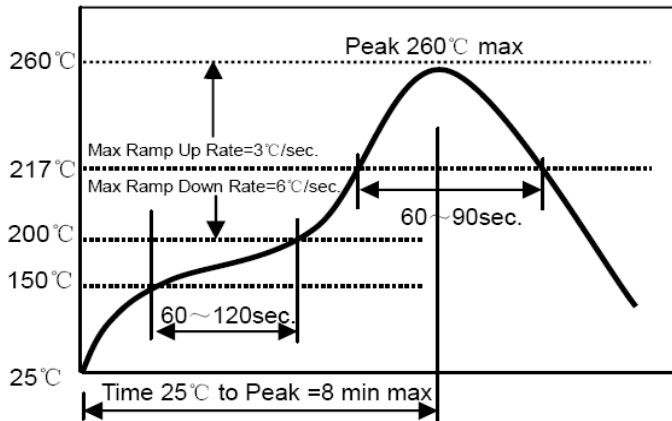
Item	Specification and Requirement	Test Method
Solderability	1. No case deformation or change in visual 2. New solder coverage More than 95%	1.Preheat: 155℃±5℃ , 60S±2S 2.Tin: lead-free. 3.Temperature:240℃±5℃, flux 3.0S±0.5S.
Mechanical shock	1. No case deformation or change in visual 2. $\Delta L/L_0 \leq \pm 10\%$	1. Acceleration: 100G 2. Pulse time: 6ms 3. 3 times in each positive and negative direction of 3 mutual perpendicular directions
Mechanical vibration	1. No case deformation or change in visual 2. $\Delta L/L_0 \leq \pm 10\%$	1. Reflow: 2times 2. Frequency: 10HZ ~ 50HZ ~ 10HZ, 20 Min/Cycles 3. Amplitude: 1.52 mm±10% 4. Directions: X,Y,Z 5. Time: 12 cycle / direction

■ Endurance Reliability

Item	Specification and Requirement	Test Method
Thermal Shock	Inductance change: Within $\pm 10\%$ Without distinct damage in visual	1. First -55℃ for 30 minutes, last 125℃ for 30 minutes as 1 cycle. Go through 1000 cycles. 2. Max transfer time is 3 minutes. 3. Measured at room temperature after placing for 24±2 hours
Biased Humidity	Inductance change: Within $\pm 10\%$ Without distinct damage in visual	1.Reflow 2 times, 2.85℃±3℃,85%±3%RH,1000 hours 3.Measured at room temperature after placing for 24±2 hours
Low temperature storage	Inductance change: Within $\pm 10\%$ Without distinct damage in visual	1. Temperature: -55 $\pm 2^\circ\text{C}$ 2. Time: 1000 hours 3. Measured at room temperature after placing for 24±2 hours
High temperature storage	Inductance change: Within $\pm 10\%$ Without distinct damage in visual	1. Temperature: +125 $\pm 2^\circ\text{C}$ 2. Time: 1000 hours 3. Measured at room temperature after placing for 24±2 hours

■ Recommended Soldering Technologies

Re-flowing Profile



Preheat condition: 150 ~200°C/60~120sec.

Allowed time above 217°C: 60~90sec.

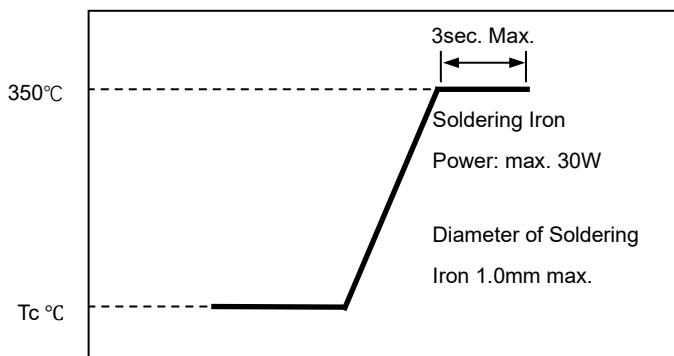
Peak temp: 260°C

Max time at Peak temp: 10 sec.

Solder paste: Sn/3.0Ag/0.5Cu

Allowed Reflow time: 2x max

Iron Soldering Profile



Iron soldering power: Max. 30W

Pre-heating: 150°C/60sec.

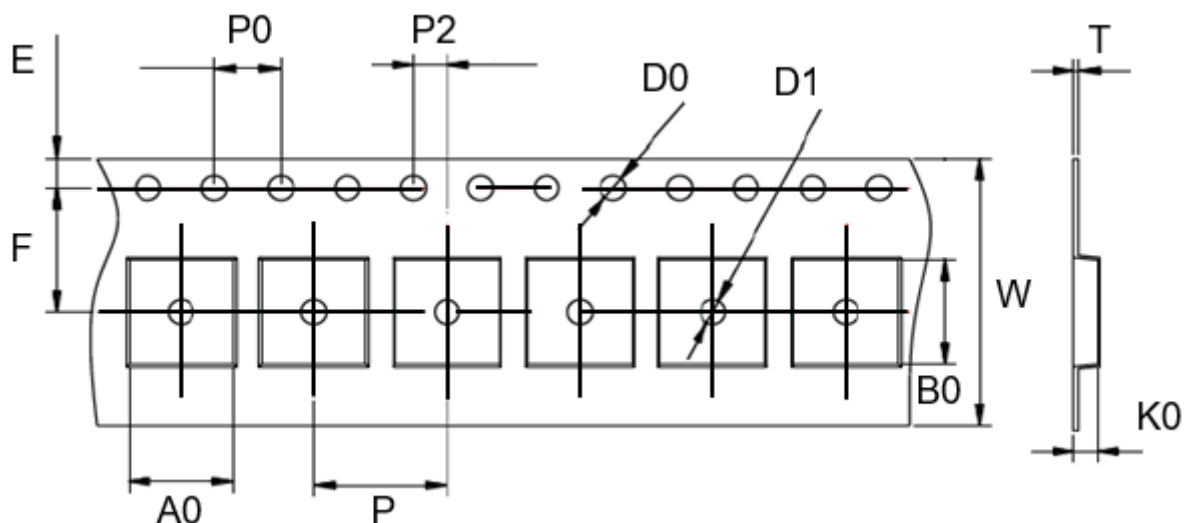
Soldering Tip temperature: 350°C Max.

Soldering time: 3sec. Max.

Solder paste: Sn/3.0Ag/0.5Cu

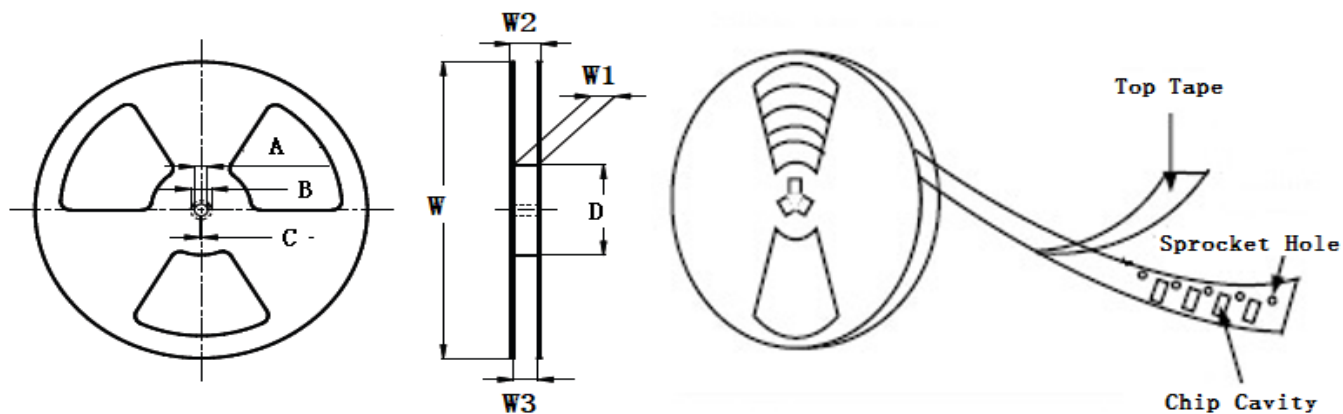
Max.1 times for iron soldering

■ Taping Dimensions(Unit:mm)



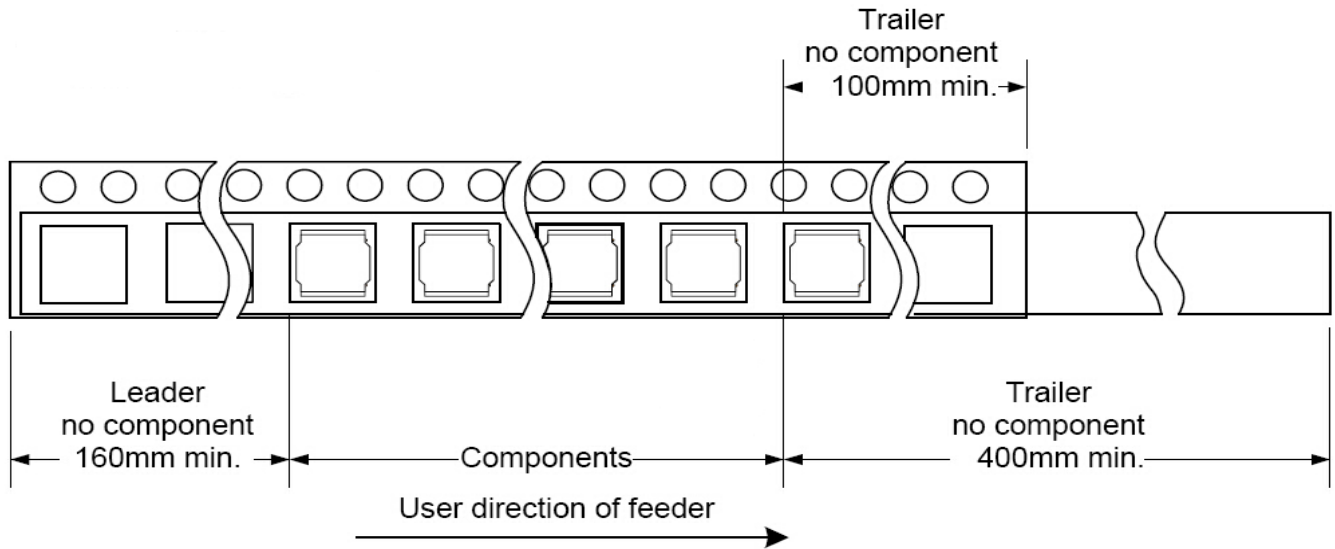
TYPE	W	P	P0	P2	D0	D1	T	A0	B0	K0	E	F	MPQ
YSPIT0630A	16 ±0.3	12 ±0.1	4 ±0.1	2 ±0.1	1.5 ±0.1	1.5 ±0.1	0.35 ±0.05	7.0 ±0.1	6.8 ±0.1	3.3 ±0.1	1.75 ±0.1	7.5 ±0.1	1000

■ Reel Dimensions(Unit:mm)

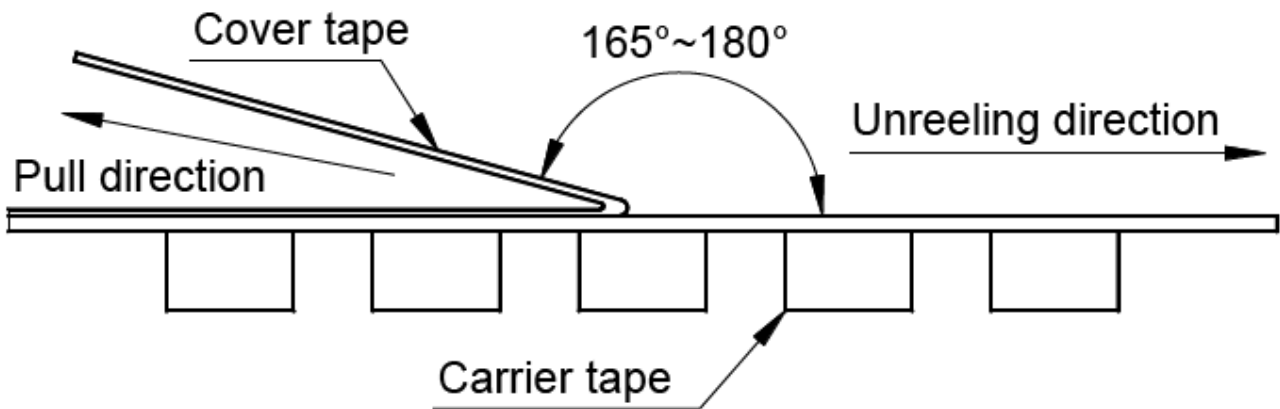


TYPE	W	W1	W2	W3	A	B	C	D
YSPIT0630A	330±2.0	16.4±2.0	22.4MAX	15.9 Min	13.0±0.5	21.0±0.8	2.0±0.5	97±0.5

■ Direction of rolling



■ Cover tape peel off condition



Cover tape peel force shall be 0.1N to 1.3N.

Reference peel speed 300±10mm/min.